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Jameco Part Number 803516



## 1.0 SCOPE

## 2.0 PRODUCT DESCRIPTION

2.2 For dimensions, materials & plating, refer to the appropriate product drawings.

The following documents are part of this specification to the extent specified herewith. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and reference documents, this specification shall take the precedence.

MIL-STD-1344 Test methods of Electrical Connector

4.1 Voltage : 125V

4.2 Current : 2.00 Amp

4.3 Operating Temperature : -55°C to + 105°C Current

<u>REVISION:</u> <div style="font-size: 2em; font-weight: bold; text-align: center;">B1</div>	<u>ECR/ECN INFORMATION:</u> <u>EC No:</u> <b>S2004-0868</b> <u>DATE:</u> <b>2004/07/20</b>	<u>TITLE:</u> <b>2MM DUAL ROW OR SINGLE ROW (SMT/ VERTICAL/ RIGHT ANGLE) HEADER</b>		<u>SHEET No.</u> <div style="font-size: 1.5em; text-align: center;">1 of 3</div>
<u>DOCUMENT NUMBER:</u> <div style="font-size: 1.2em; font-weight: bold; text-align: center;">PS-87761-100</div>		<u>CREATED / REVISED BY:</u> <div style="text-align: center;">AI TING</div>	<u>CHECKED BY:</u> <div style="text-align: center;">KCLING</div>	<u>APPROVED BY:</u> <div style="text-align: center;">SKTOH</div>
<div style="text-align: right; font-size: 0.8em;">TEMPLATE FILENAME: PRODUCT_SPEC[SIZE_A4](V.1).DOC</div>				



# PRODUCT SPECIFICATION

## 5.0 PERFORMANCE

### 5.1 ELECTRICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
1	<b>Capacitance</b>	Measure between adjacent terminals	1.2 pf max
2	<b>Insulation Resistance</b>	Test between adjacent contact at 500 V DC for 1 minute, per (MIL-STD-1344 MTD 3001.1)	1000 Megaohms minimum
3	<b>Dielectric Strength</b>	Test between adjacent contact at 500VAC rms and 1 minute hold time.	No breakdown

### 5.2 MECHANICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
4	<b>Pin Retention Force in Housing</b>	Push pin axially from housing at a rate of 12.7mm/min (0.50 inch/min)	0.85 Kgf min

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<b>PS-87761-100</b>	<b>AI TING</b>	<b>KCLING</b>	<b>SKTOH</b>



# PRODUCT SPECIFICATION

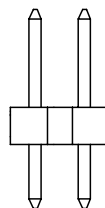
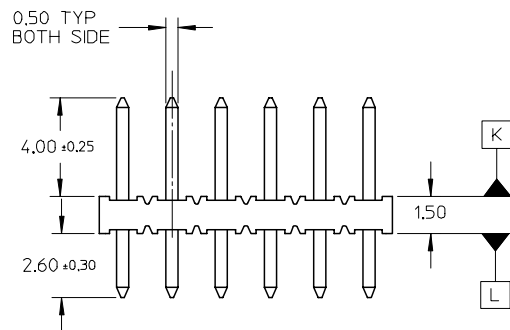
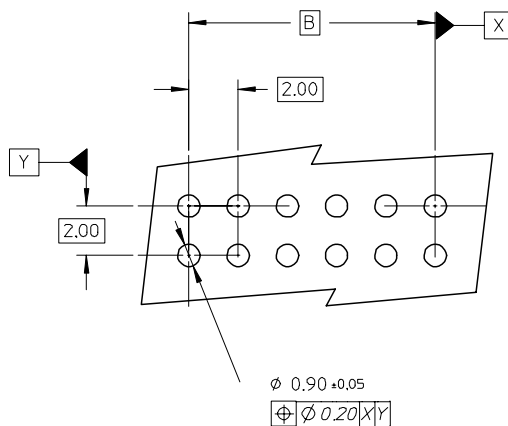
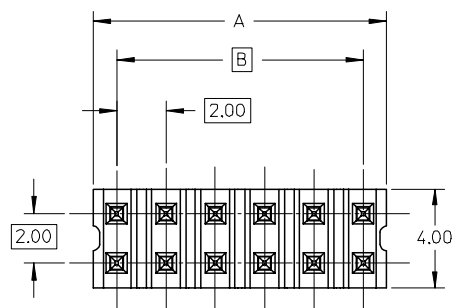
## 5.3 ENVIRONMENTAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
5	Temperature Rise	Apply 2 amps DC to the header and measure contact temperature rise for 48 hours	30°C maximum temperature rise above ambient.
6	Solderability	Solder Time: 5 ± 0.5 sec. Solder Temperature: 245 ±5 °C	Soldertail should have 95% continuous new solder coating coverage (Apply to non-kinked Soldertail only)
7	Resistance to Soldering Heat (Wave Soldering) For Series a)87760,  b)87758, 87830, 87761  c) Other series	Sample mounted on PCB and subject to wave soldering,  a)Temperature : 260 ±5 °C for 12 ± 2 Sec  b)Temperature : 245 ±5 °C for 3Sec  c) Temperature : 245 ±5 °C for 5Sec	Appearance : No Damage
8	Resistance to Solder Heat (Reflow) For Series 87759, 87762	Sample mounted on PCB and subject to reflow, Temperature : 245 ±5 °C for 10 ±2 Sec	Appearance : No Damage

## 6.0 Packaging

Product shall be packaged and protected against damage during handling, transportation and storage.

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DOCUMENT NUMBER:	CREATED / REVISED BY:	CHECKED BY:	APPROVED BY:
<b>PS-87761-100</b>	<b>AI TING</b>	<b>KCLING</b>	<b>SKTOH</b>



**LEGEND**  
87758- \* \* \* \*  
CKT SIZE (SEE SHT 2 TABLE) PLATING (SEE NOTE 2)

#### NOTES:

##### 1. MATERIAL:

HOUSING: 30% G.F. NYLON 46, 94V-0, COLOR: BLACK  
PIN: 0.50mm SQ. PHOSPHOR BRONZE 510

##### 2. PLATING:

\*\*16 - 0.38um MIN GOLD IN CONTACT AREA.  
TIN IN SOLDER AREA, BOTH OVER  
NICKEL OVERALL.  
\*\*17 - 0.76um MIN GOLD IN CONTACT AREA.  
TIN IN SOLDER AREA, BOTH OVER  
NICKEL OVERALL.  
\*\*18 - 2.54um MIN TIN OVER  
NICKEL OVERALL.

3. 12 CKT USED FOR ILLUSTRATION ONLY

4. PACKED IN POCKET TRAY

5. PIN PUSHOUT FORCE: 1KG MIN IN EITHER DIRECTION

6. CKT 4 AND 6 IS CUT FROM CKT 8 AND 12 RESPECTIVELY.  
CKT 2 ARE CUT FROM ANY LARGER CKT SIZE. ROUGH EDGES  
ARE EXPECTED ALONG THE CUTTING EDGES.

7. PRODUCT SPEC PS-87761-100 APPLIES.

8. RECOMMENDED PCB THICKNESS IS 1.60 ± 0.10

Ø 0.71 ± 0.07  
Ø 0.30 (M) K



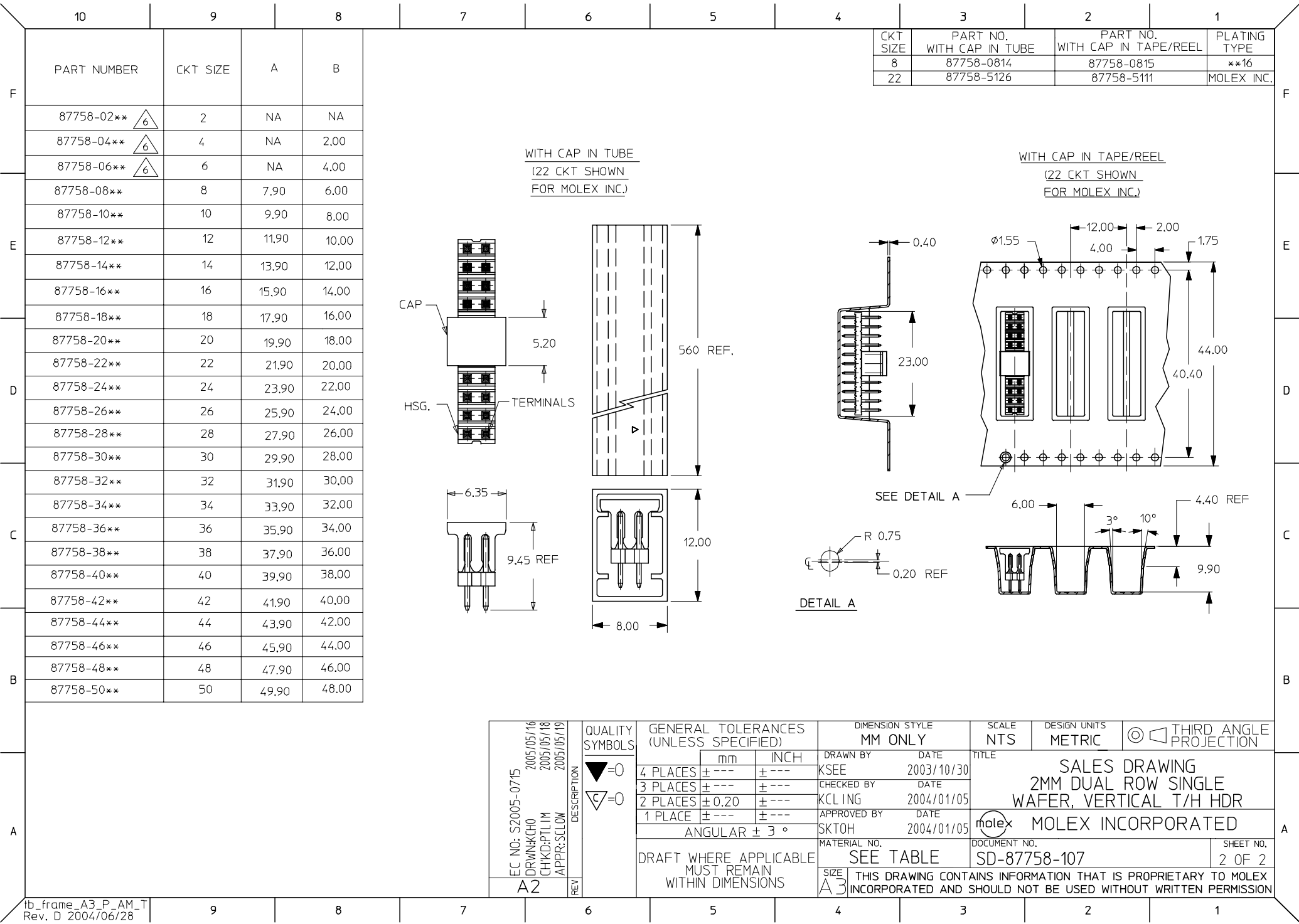
VIEW P

Ø 0.71 ± 0.07  
Ø 0.30 (M) L

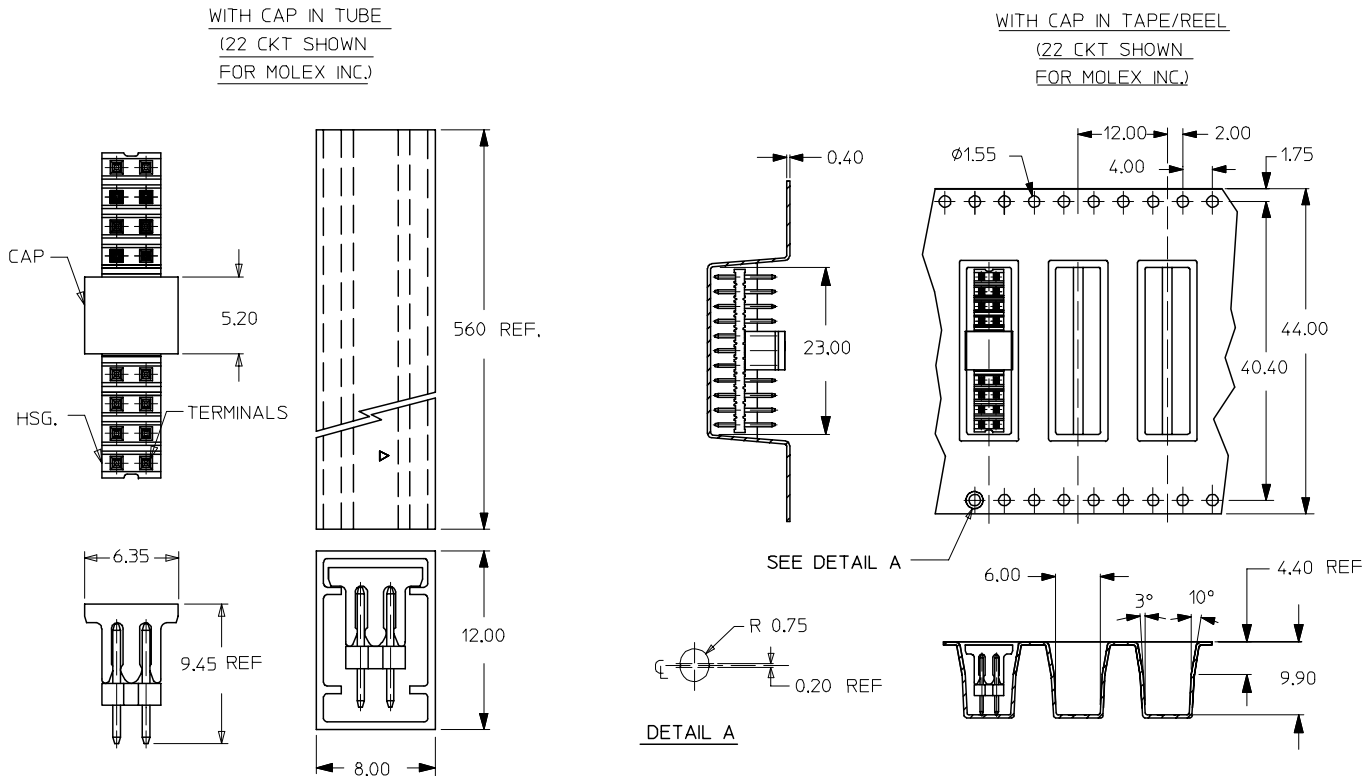


VIEW Q

EC NO: S2005-0715 2005/05/16 DRWN:KCH0 CHKD:PTLIM APPR:SCLOW 2005/05/18 2005/05/19	DESCRIPTION	QUALITY SYMBOLS  ▽=0 ▽C=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
				mm	INCH	DRAWN BY KSEE	DATE 2003/10/30	TITLE SALES DRAWING 2MM DUAL ROW SINGLE WAFER, VERTICAL T/H HDR				
			4 PLACES	± ---	± ---	CHECKED BY KCL ING	DATE 2004/01/05					
			3 PLACES	± ---	± ---	APPROVED BY	DATE					
			2 PLACES	± 0.20	± ---	SKTOH	2004/01/05					
			1 PLACE	± ---	± ---	ANGULAR ± 3 °		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-87758-107	SHEET NO. 1 OF 2	
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



CKT SIZE	PART NO. WITH CAP IN TUBE	PART NO. WITH CAP IN TAPE/REEL	PLATING TYPE
8	87758-0814	87758-0815	**16
22	87758-5126	87758-5111	MOLEX INC.



EC NO: S2005-0715 2005/05/16 DRWN:KCH0 2005/05/18 CHKD:PTLIM 2005/05/19 APPR:SCLOW	DESCRIPTION	QUALITY SYMBOLS  ▽=0  ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
				mm	INCH	DRAWN BY	DATE	TITLE  SALES DRAWING 2MM DUAL ROW SINGLE WAFER, VERTICAL T/H HDR  MOLEX MOLEX INCORPORATED				
			4 PLACES	± ---	± ---	KSEE	2003/10/30					
			3 PLACES	± ---	± ---	CHECKED BY	DATE					
			2 PLACES	± 0.20	± ---	KCL ING	2004/01/05	DOCUMENT NO. SD-87758-107				
			1 PLACE	± ---	± ---	APPROVED BY	DATE					
ANGULAR ± 3 °			SKTOH	2004/01/05								
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			MATERIAL NO.		SEE TABLE							
			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							